

MOSFET – Dual P-Channel, 1.8 V Specified, POWERTRENCH[®]

-12 V, -2.5 A

FDC6318P

General Description

These P-Channel 1.8 V specified MOSFETs are produced using onsemi's advanced POWERTRENCH process that has been especially tailored to minimize on-state resistance and yet maintain low gate charge for superior switching performance.

Features

- -2.5 A, -12 V
 - ♦ $R_{DS(on)} = 90\text{ m}\Omega$ at $V_{GS} = -4.5\text{ V}$
 - ♦ $R_{DS(on)} = 125\text{ m}\Omega$ at $V_{GS} = -2.5\text{ V}$
 - ♦ $R_{DS(on)} = 200\text{ m}\Omega$ at $V_{GS} = -1.8\text{ V}$
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- SUPERSOT[™]-6 Package: Small Footprint (72% smaller than Standard SO-8) Low Profile (1 mm thick)
- This Device is Pb-Free, Halide Free and is RoHS Compliant

Applications

- Power Management
- Load Switch

MOSFET MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

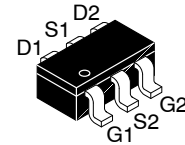
Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		-12	V
V_{GSS}	Gate-Source Voltage		± 8	V
I_D	Drain Current	Continuous (Note 1a)	-2.5	A
		Pulsed	-7	
P_D	Power Dissipation for Single Operation	(Note 1a)	0.96	W
		(Note 1b)	0.9	
		(Note 1c)	0.7	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		-55 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

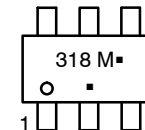
Symbol	Parameter	Ratings	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	130	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	60	$^\circ\text{C/W}$

V_{DSS}	$R_{DS(on)}\text{ MAX}$	$I_D\text{ MAX}$
-12 V	90 m Ω @ -4.5 V	-2.5 A
	125 m Ω @ -2.5 V	
	200 m Ω @ -1.8 V	



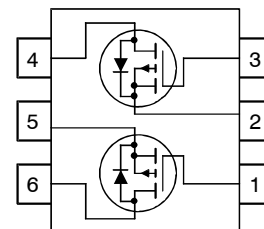
**TSOT23 6-Lead
SUPERSOT[™]-6
CASE 419BL**

MARKING DIAGRAM



318 = Specific Device Code
 M = Date Code
 ■ = Pb-Free Package
 (Note: Microdot may be in either location)

PINOUT



ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

FDC6318P

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain–Source Breakdown Voltage	I _D = –250 μA, V _{GS} = 0 V	–12			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = –250 μA, Referenced to 25°C		–2.9		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = –10 V, V _{GS} = 0 V			–1	μA
I _{GSSF}	Gate–Body Leakage, Forward	V _{GS} = 8 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate–Body Leakage, Reverse	V _{GS} = –8 V, V _{DS} = 0 V			–100	nA

ON CHARACTERISTICS (Note 2)

V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = –250 μA	–0.4	–0.7	–1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I _D = –250 μA, Referenced to 25°C		2.3		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	V _{GS} = –4.5 V, I _D = –2.5 A		69	90	mΩ
		V _{GS} = –2.5 V, I _D = –2 A		93	125	
		V _{GS} = –1.8 V, I _D = –1.6 A		135	200	
		V _{GS} = –4.5 V, I _D = –2.5 A, T _J = 125°C		85	120	
I _{D(on)}	On–State Drain Current	V _{GS} = –4.5 V, V _{DS} = –5 V	–6			A
g _{FS}	Forward Transconductance	V _{DS} = –5 V, I _D = –2.5 A		8		S

DYNAMIC CHARACTERISTICS

C _{iss}	Input Capacitance	V _{DS} = –6 V, V _{GS} = 0 V, f = 1.0 MHz		455		pF
C _{oss}	Output Capacitance			194		pF
C _{rss}	Reverse Transfer Capacitance			134		pF

SWITCHING CHARACTERISTICS (Note 2)

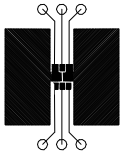
t _{d(on)}	Turn–On Delay Time	V _{DD} = –6 V, I _D = –1 A, V _{GS} = –4.5 V, R _{GEN} = 6 Ω		9	18	ns
t _r	Turn–On Rise Time			14	25	ns
t _{d(off)}	Turn–Off Delay Time			21	34	ns
t _f	Turn–Off Fall Time			17	31	ns
Q _g	Total Gate Charge	V _{DS} = –6 V, I _D = –2.5 A, V _{GS} = –4.5 V		5.4	8	nC
Q _{gs}	Gate to Source Gate Charge			1.1		nC
Q _{gd}	Gate to Drain “Miller” Charge			1.3		nC

DRAIN–SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

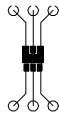
I _S	Maximum Continuous Drain–Source Diode Forward Current				–0.8	A
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = –0.8 A (Note 2)		–0.7	–1.2	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

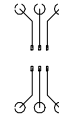
- R_{θJA} is the sum of the junction–to–case and case–to–ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.



a. 130°C/W when mounted on a 0.125 in² pad of 2 oz. copper



b. 140°C/W when mounted on a .004 in² pad of 2 oz. copper



c. 180°C/W when mounted on a minimum pad

- Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0 %.

TYPICAL CHARACTERISTICS

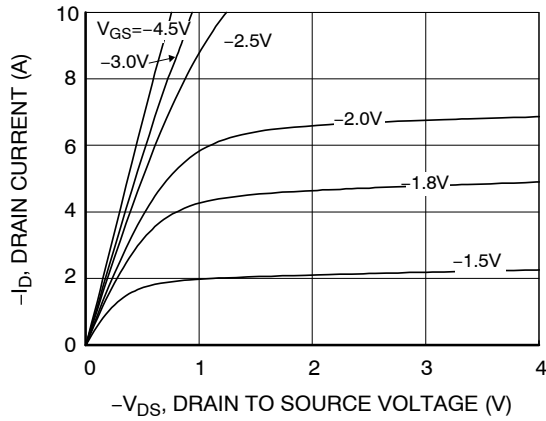


Figure 1. On-Region Characteristics

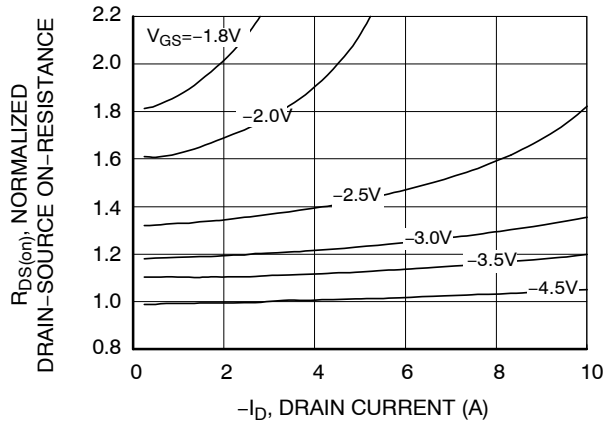


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

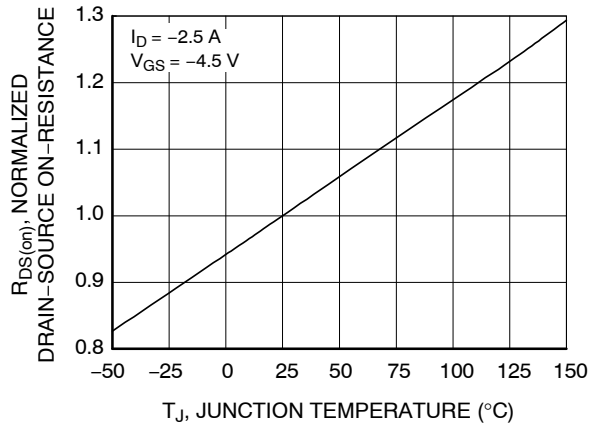


Figure 3. On-Resistance variation with Temperature

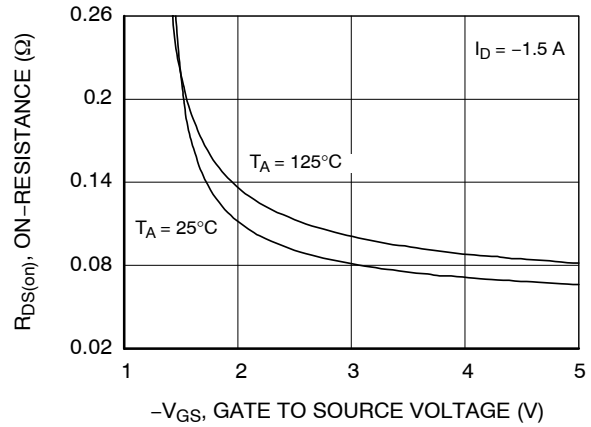


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

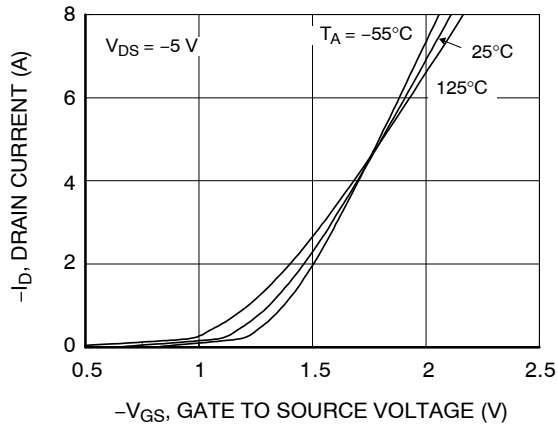


Figure 5. Transfer Characteristics

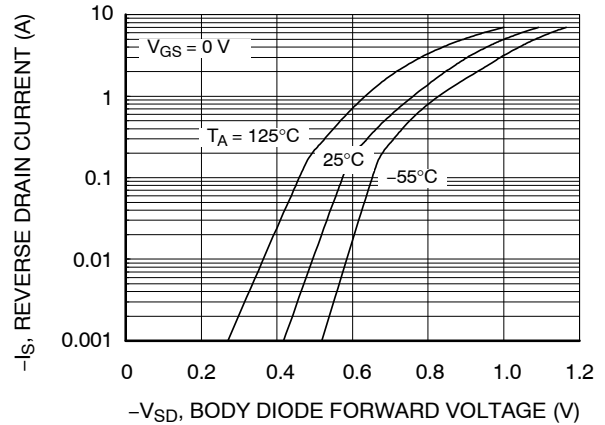


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

TYPICAL CHARACTERISTICS (continued)

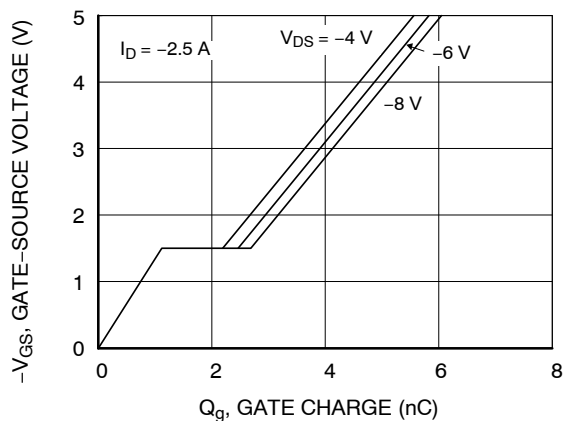


Figure 7. Gate Charge Characteristics

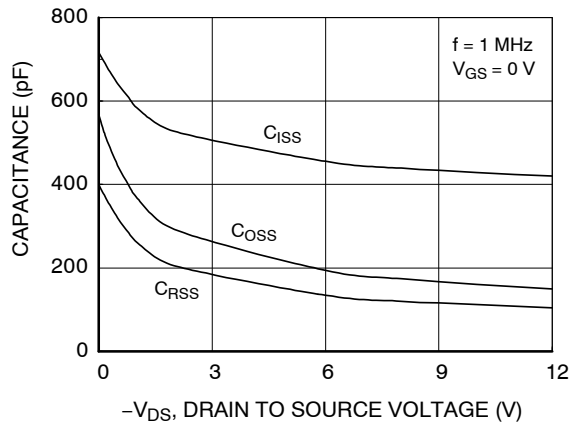


Figure 8. Capacitance Characteristics

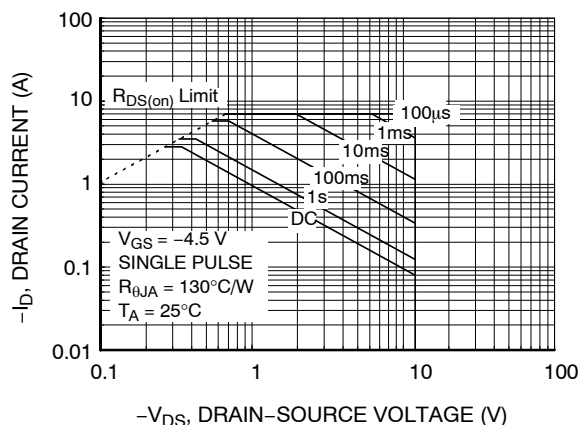


Figure 9. Maximum Safe Operating Area

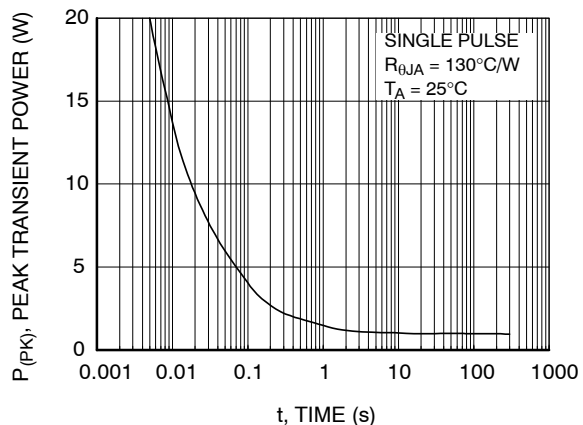
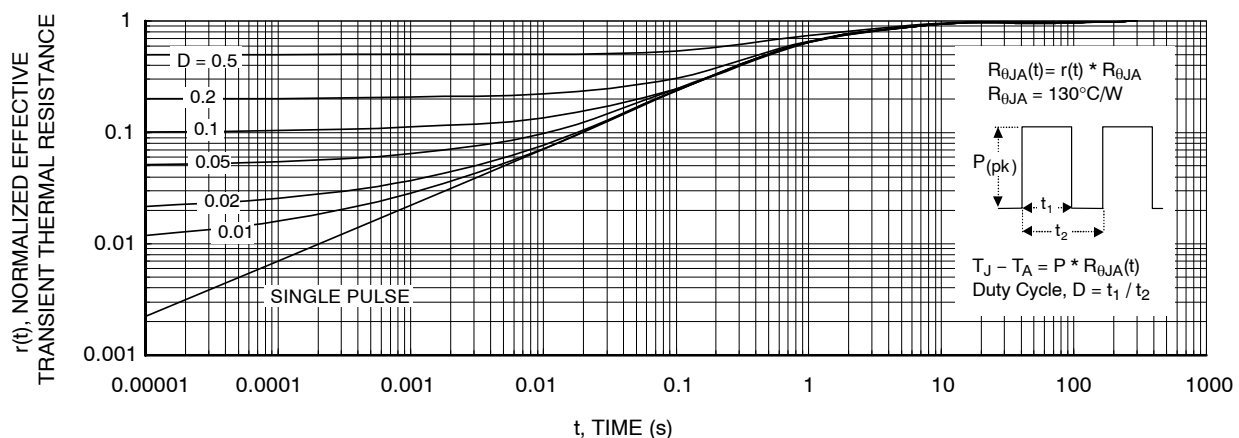


Figure 10. Single Pulse Maximum Power Dissipation



Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.

Figure 11. Transient Thermal Response Curve

FDC6318P

ORDERING INFORMATION

Device	Device Marking	Package Type	Shipping [†]
FDC6318P	318	TSOT-23-6 (Pb-Free, Halide Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

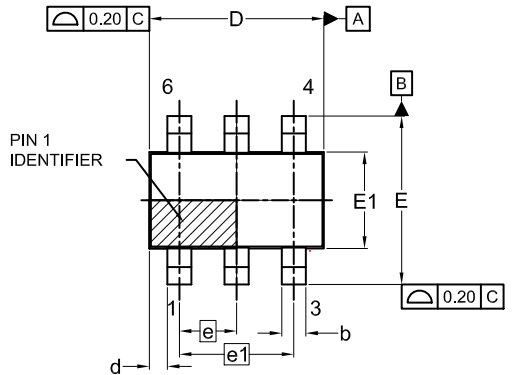
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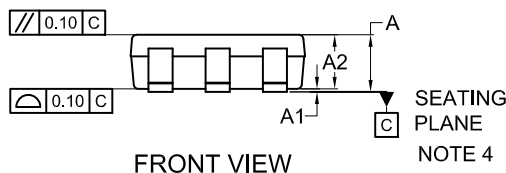
SCALE 2:1

TSOT23 6-Lead
CASE 419BL
ISSUE A

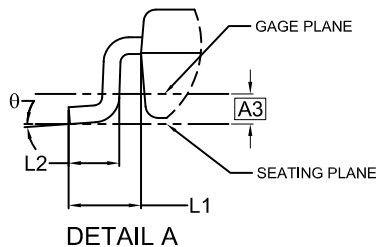
DATE 31 AUG 2020



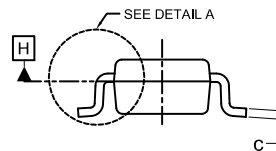
TOP VIEW



FRONT VIEW

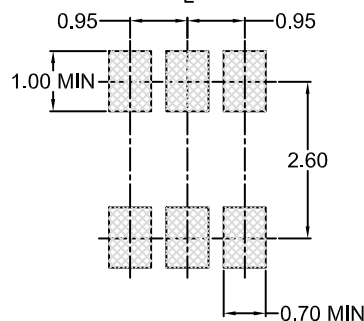


DETAIL A



SIDE VIEW

SYMM

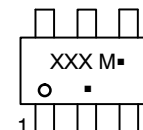

LAND PATTERN
RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR
PB-FREE STRATEGY AND SOLDERING DETAILS,
PLEASE DOWNLOAD THE ON SEMICONDUCTOR
SOLDERING AND MOUNTING TECHNIQUES
REFERENCE MANUAL, SOLDERM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.25MM PER END. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
4. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	0.05	0.10
A2	0.70	0.85	1.00
A3	0.25 BSC		
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.80	2.95	3.10
d	0.30 REF		
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.95 BSC		
e1	1.90 BSC		
L1	0.60 REF		
L2	0.20	0.40	0.60
Θ	0°	—	10°

**GENERIC
MARKING DIAGRAM***


XXX = Specific Device Code

M = Date Code

▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TSOT23 6-Lead	PAGE 1 OF 1

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